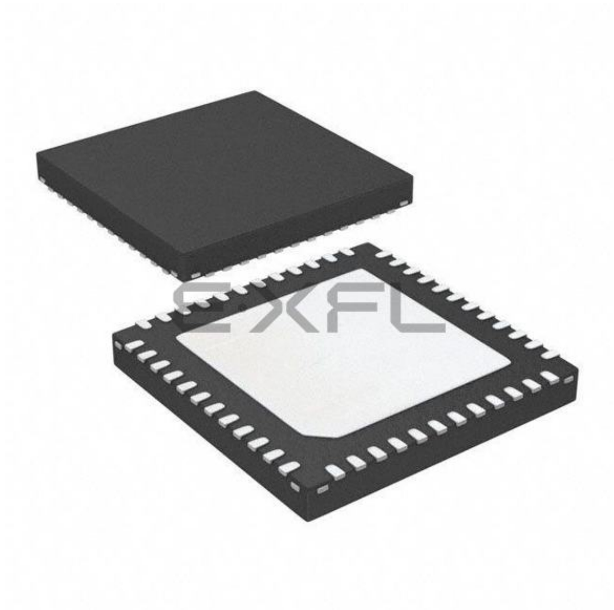


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	CANbus, DALI, I²C, SCI, SPI, UART/USART, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 15x14b; D/A 3x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-WFQFN Exposed Pad
Supplier Device Package	48-HWQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r7fs128783a01cne-ac1

Table 1.4 Event Link

Feature	Functional description
Event Link Controller (ELC)	The Event Link Controller (ELC) uses the interrupt requests generated by various peripheral modules as event signals to connect them to different modules, enabling direct interaction between the modules without CPU intervention. See section 16, Event Link Controller in User's Manual.

Table 1.5 Direct memory access

Feature	Functional description
Data Transfer Controller (DTC)	A Data Transfer Controller (DTC) module is provided for transferring data when activated by an interrupt request. See section 15, Data Transfer Controller (DTC) in User's Manual.

Table 1.6 Timers

Feature	Functional description
General PWM Timer (GPT)	The General PWM Timer (GPT) is a 32-bit timer with 1 channel and a 16-bit timer with 6 channels. PWM waveforms can be generated by controlling the up-counter, down-counter, or the up- and down-counter. In addition, PWM waveforms can be generated for controlling brushless DC motors. The GPT can also be used as a general-purpose timer. See section 20, General PWM Timer (GPT) in User's Manual.
Port Output Enable for GPT (POEG)	Use the Port Output Enable for GPT (POEG) function to place the General PWM Timer (GPT) output pins in the output disable state. See section 19, Port Output Enable for GPT (POEG) in User's Manual.
Asynchronous General Purpose Timer (AGT)	The Asynchronous General Purpose Timer (AGT) is a 16-bit timer that can be used for pulse output, external pulse width or period measurement, and counting external events. This 16-bit timer consists of a reload register and a down-counter. The reload register and the down-counter are allocated to the same address, and they can be accessed with the AGT register. See section 22, Asynchronous General Purpose Timer (AGT) in User's Manual.
Realtime Clock (RTC)	The Realtime Clock (RTC) has two counting modes, calendar count mode and binary count mode, that are controlled by the register settings. For calendar count mode, the RTC has a 100-year calendar from 2000 to 2099 and automatically adjusts dates for leap years. For binary count mode, the RTC counts seconds and retains the information as a serial value. Binary count mode can be used for calendars other than the Gregorian (Western) calendar. See section 23, Realtime Clock (RTC) in User's Manual.

Table 1.7 Communication interfaces (1 of 2)

Feature	Functional description
Serial Communications Interface (SCI)	The Serial Communication Interface (SCI) is configurable to five asynchronous and synchronous serial interfaces: • Asynchronous interfaces (UART and asynchronous communications interface adapter (ACIA)) • 8-bit clock synchronous interface • Simple IIC (master-only) • Simple SPI • Smart card interface. The smart card interface complies with the ISO/IEC 7816-3 standard for electronic signals and transmission protocol. SCI0 has FIFO buffers to enable continuous and full-duplex communication, and the data transfer speed can be configured independently using an on-chip baud rate generator. See section 27, Serial Communications Interface (SCI) in User's Manual.
Digital Addressable Lighting Interface (DALI)	A Digital Addressable Lighting Interface (DALI) module is provided. DALI is an international open lighting control communication protocol that includes dimming control of electronic ballasts and LED lights from different manufacturers. The DALI interface module is designed to allow compliance with international standard IEC62386-101 Edition 1.0/2.0 (DALI 2), that includes software control. See section 28, Digital Addressable Lighting Interface (DALI) in User's Manual.

Table 1.7 Communication interfaces (2 of 2)

Feature	Functional description
I^2C Bus interface (IIC)	A 2-channel IIC module conforms with and provides a subset of the NXP I^2C bus (Inter-Integrated Circuit bus) interface functions. See section 29, I^2C Bus Interface (IIC) in User's Manual.
Serial Peripheral Interface (SPI)	Two independent Serial Peripheral Interface (SPI) channels are capable of high-speed, full-duplex synchronous serial communications with multiple processors and peripheral devices. See section 31, Serial Peripheral Interface (SPI) in User's Manual.
CAN Module (CAN)	The Controller Area Network (CAN) module provides functionality to receive and transmit data using a message-based protocol between multiple slaves and masters in electromagnetically noisy applications. The CAN module complies with the ISO 11898-1 (CAN 2.0A/CAN 2.0B) standard and supports up to 32 mailboxes, which can be configured for transmission or reception in normal mailbox and FIFO modes. Both standard (11-bit) and extended (29-bit) messaging formats are supported. See section 30, Controller Area Network (CAN) in User's Manual.
USB 2.0 Full-Speed Module (USBFS)	The USBFS is a USB controller that can operate as a host controller or device controller. The module supports full-speed and low-speed transfer as defined in the Universal Serial Bus Specification 2.0. The module has an internal USB transceiver and supports all of the transfer types defined in the Universal Serial Bus Specification 2.0. The USB has buffer memory for data transfer, providing a maximum of 5 pipes. PIPE0 and PIPE4 to PIPE7 can be assigned any endpoint number based on the peripheral devices used for communication or based on the user system. The MCU supports revision 1.2 of the Battery Charging Specification. Because the MCU can be powered at 5 V, the USB LDO regulator provides the internal USB transceiver power supply at 3.3 V. See section 26, USB 2.0 Full-Speed Module (USBFS) in User's Manual.

Table 1.8 Analog

Feature	Functional description
14-bit A/D Converter (ADC14)	A 14-bit successive approximation A/D converter is provided. Up to 21 analog input channels are selectable. Temperature sensor output and internal reference voltage are selectable for conversion. The A/D conversion accuracy is selectable from 12-bit and 14-bit conversion making it possible to optimize the tradeoff between speed and resolution in generating a digital value. See section 33, 14-Bit A/D Converter (ADC14) in User's Manual.
8-bit D/A Converter (DAC8)	An 8-bit D/A converter (DAC8) is provided. See section 34, 8-Bit D/A Converter (DAC8) in User's Manual.
Temperature Sensor (TSN)	The on-chip temperature sensor determines and monitors the die temperature for reliable operation of the device. The sensor outputs a voltage directly proportional to the die temperature, and the relationship between the die temperature and the output voltage is linear. The output voltage is provided to the ADC for conversion and can be further used by the end application. See section 35, Temperature Sensor (TSN) in User's Manual.
High-Speed Analog Comparator (ACMPHS)	The analog comparator compares a test voltage with a reference voltage and to provide a digital output based on the result of conversion. Both the test voltage and the reference voltage can be provided to the ACMPHS from internal sources (D/A converter output) and an external source. Such flexibility is useful in applications that require go/no-go comparisons to be performed between analog signals without necessarily requiring A/D conversion. See section 37, High-Speed Analog Comparator (ACMPHS) in User's Manual.
Low-Power Analog Comparator (ACMPLP)	The analog comparator compares a reference input voltage and analog input voltage. The comparison result can be read by software and also be output externally. The reference input voltage can be selected from either an input to the CMPREFi (i = 0, 1) pin, an output from internal D/A converter, or from the internal reference voltage (Vref) generated internally in the MCU. The ACMPLP response speed can be set before starting an operation. Setting high-speed mode decreases the response delay time, but increases current consumption. Setting low-speed mode increases the response delay time, but decreases current consumption. See section 38, Low-Power Analog Comparator (ACMPLP) in User's Manual.
Operational Amplifier (OPAMP)	The operational amplifier amplifies small analog input voltages and outputs the amplified voltages. A total of four differential operational amplifier units with two input pins and one output pin are provided. See section 36, Operational Amplifier (OPAMP) in User's Manual.

R7FS128782A01CLM

	A	B	C	D	E	F	
6	P015	P100	P112	P111	P108 /SWDIO	P300 /SWCLK	6
5	P014	P013	P101	P110	P200	VCC_USB _LDO	5
4	AVCC0	P012	P102	P109	P201/MD	VCC_USB	4
3	AVSS0	P011 /VREFL0	P103	P213 /XTAL	RES	P914 /USB_DP	3
2	P010 /VREFH0	P000	P001	P212 /EXTAL	P407	P915 /USB_DM	2
1	VCL	P215 /XCIN	P214 /XCOUT	VSS/ VSS_USB	VCC	P002	1
	A	B	C	D	E	F	

Figure 1.6 Pin assignment for LGA 36-pin (top view, pad side down)

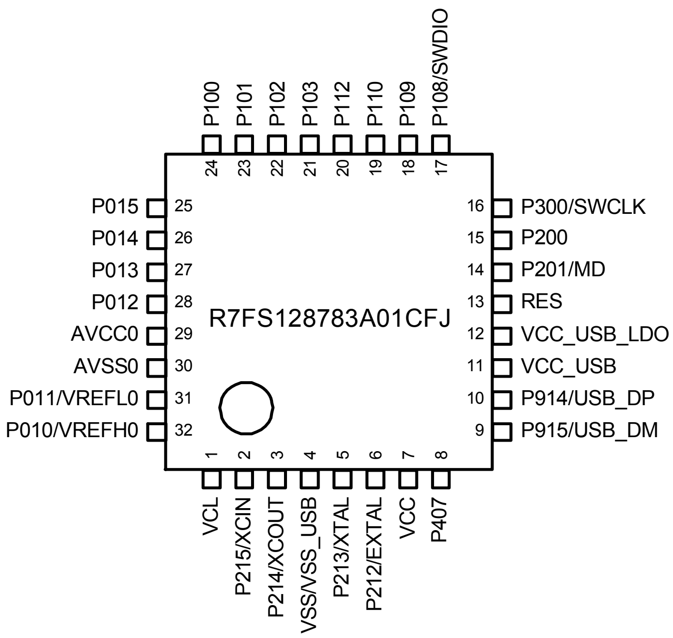


Figure 1.7 Pin assignment for LQFP 32-pin

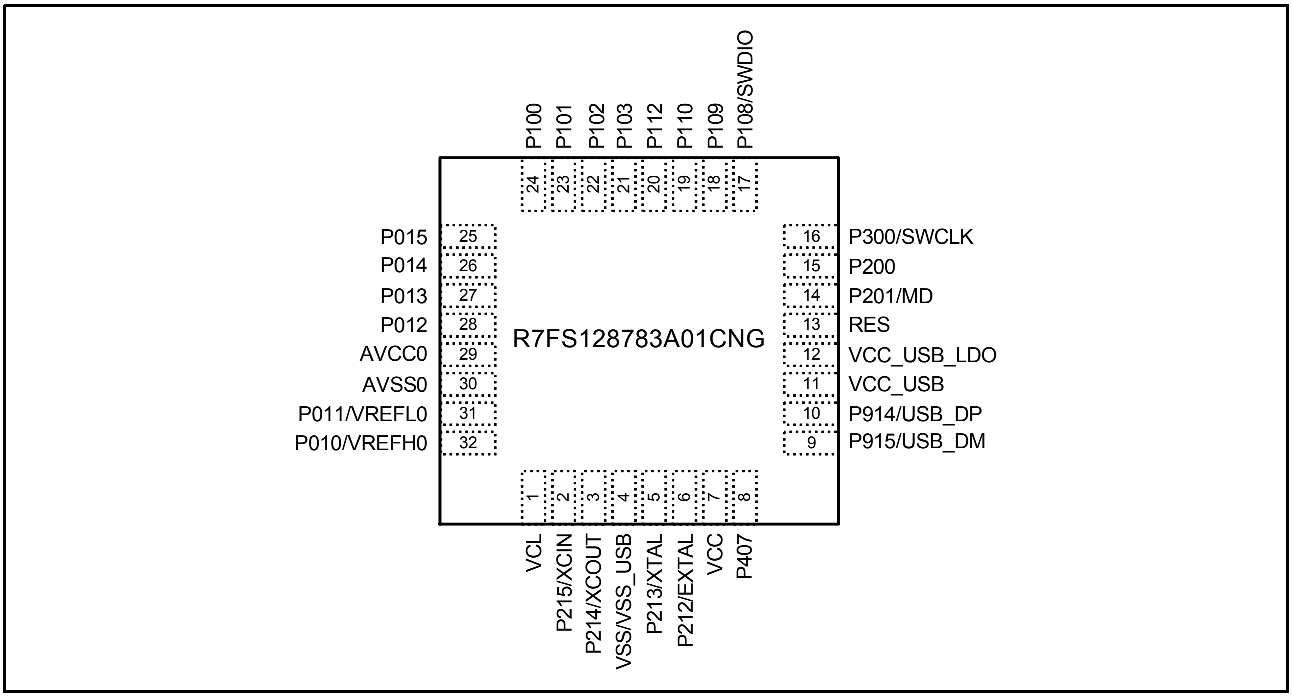


Figure 1.8 Pin assignment for QFN 32-pin

1.7 Pin Lists

Pin number								Timers				Communication Interfaces				Analogs				HMI	
LQFP64	LQFP48	QFN48	LGA36	LQFP32	QFN32	Power, System, Clock, Debug, CAC	I/O ports	AGT	GPT_OPS, POEG	GPT	RTC	USBFS,CAN, DALI	SCI	IIC	SPI	ADC14	DAC8	ACMPHS, ACMPLP	OPAMP	CTSU	Interrupt
1	1	1	-	-	-	CACREF_C	P400	AGTIO1_D		GTIOC6A_A			SCK0_B/SCK1_B	SCL0_A						TS20	IRQ0
2	2	2	-	-	-		P401		GTETRGA_B	GTIOC6B_A		CTX0_B	CTS0_RTS0_B/SS0_B/TXD1_B/MOSI1_B/SDA1_B	SDA0_A						TS19	IRQ5
3	-	-	-	-	-		P402			GTIOC3B_B		CRX0_B	RXD1_B/MISO1_B/SCL1_B							TS18	IRQ4
4	-	-	-	-	-		P403			GTIOC3A_B			CTS1_RTS1_B/SS1_B							TS17	
5	3	3	A1	1	1	VCL															
6	4	4	B1	2	2	XCIN	P215														
7	5	5	C1	3	3	XCOUT	P214														
8	6	6	D1	4	4	VSS															
9	7	7	D3	5	5	XTAL	P213		GTETRGA_D	GTIOC0A_D			TXD1_A/MOSI1_A/SDA1_A								IRQ2
10	8	8	D2	6	6	EXTAL	P212	AGTEE1	GTETRGB_D	GTIOC0B_D			RXD1_A/MISO1_A/SCL1_A								IRQ3
11	9	9	E1	7	7	VCC															
12	-	-	-	-	-		P411	AGTOA1	GTOVUP_B	GTIOC6A_B			TXD0_B/MOSI0_B/SDA0_B		MOSIA_B					TS07	IRQ4
13	-	-	-	-	-		P410	AGTOB1	GTOVLO_B	GTIOC6B_B			RXD0_B/MISO0_B/SCL0_B		MISOA_B					TS06	IRQ5
14	10	10	-	-	-		P409		GTOWUP_B	GTIOC5A_B			TXD0_E/MOSI0_E/SDA0_E/TXD9_A/MOSI9_A/SDA9_A							TS05	IRQ6
15	11	11	-	-	-		P408		GTOWLO_B	GTIOC5B_B			RXD9_A/MISO9_A/SCL9_A	SCL0_C						TS04	IRQ7
16	12	12	E2	8	8		P407	AGTIO0_C		GTIOC0A_E	RTCOUT	USB_VBUS	CTS0_RTS0_D/SS0_D	SDA0_B	SSLB3_A	ADTRG0_B				TS03	
17	13	13	D1	4	4	VSS_USB															

Pin number						Power, System, Clock, Debug, CAC	I/O ports	Timers				Communication Interfaces				Analogs				HMI	
LQFP64	LQFP48	QFN48	LGA36	LQFP32	QFN32			AGT	GPT_OPS, POEG	GPT	RTC	USBFS,CAN, DALI	SCI	IIC	SPI	ADC14	DAC8	ACMPHS, ACMPLP	OPAMP	CTSU	Interrupt
56	42	42	A4	29	29	AVCC0															
57	43	43	A3	30	30	AVSS0															
58	44	44	B3	31	31	VREFL0	P011									AN006	DA2_A		AMP2O		
59	45	45	A2	32	32	VREFH0	P010									AN005			AMP1O		
60	-	-	-	-	-		P004									AN004	DA2_B			TS25	IRQ3
61	-	-	-	-	-		P003									AN003			AMP3O		
62	46	46	F1	-	-		P002									AN002			AMP0O		IRQ2
63	47	47	C2	-	-		P001									AN001		IVREF2	AMP0-	TS22	IRQ7
64	48	48	B2	-	-		P000									AN000		IVCMP2	AMP0+	TS21	IRQ6

Note: Several pin names have the added suffix of _A, _B, _C, _D and _E. The suffix can be ignored when assigning functionality.

Table 2.2 Recommended operating conditions

Parameter	Symbol	Value	Min	Typ	Max	Unit
Power supply voltages	VCC[*1, *2]	When USBFS is not used	1.6	-	5.5	V
		When USBFS is used USB Regulator Disable	VCC_USB	-	3.6	V
		When USBFS is used USB Regulator Enable	VCC_USB_LDO	-	5.5	V
	VSS		-	0	-	V
USB power supply voltages	VCC_USB	When USBFS is not used	-	VCC	-	V
		When USBFS is used USB Regulator Disable (Input)	3.0	3.3	3.6	V
	VCC_USB_LDO	When USBFS is not used	-	VCC	-	V
		When USBFS is used USB Regulator Enable	3.8	-	5.5	V
	VSS_USB		-	0	-	V
Analog power supply voltages	AVCC0[*1, *2]		1.6	-	5.5	V
	AVSS0		-	0	-	V
	VREFH0	When used as ADC14 Reference	1.6	-	AVCC0	V
	VREFL0		-	0	-	V

Note 1. Use AVCC0 and VCC under the following conditions:
AVCC0 and VCC can be set individually within the operating range when VCC ≥ 2.0 V
AVCC0 = VCC when VCC < 2.0 V.

Note 2. When powering on the VCC and AVCC0 pins, power them on at the same time or the VCC pin first and then the AVCC0 pin.

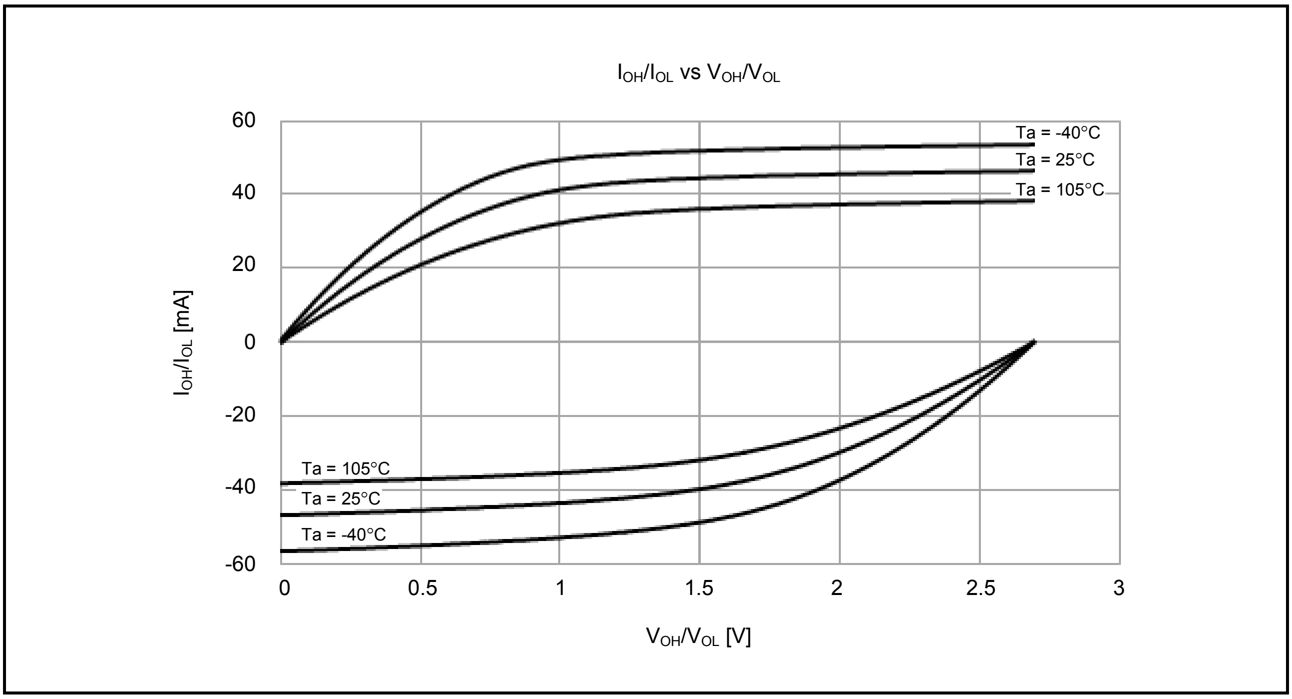


Figure 2.13 V_{OH}/V_{OL} and I_{OH}/I_{OL} temperature characteristics at VCC = 2.7 V when middle drive output is selected (reference data)

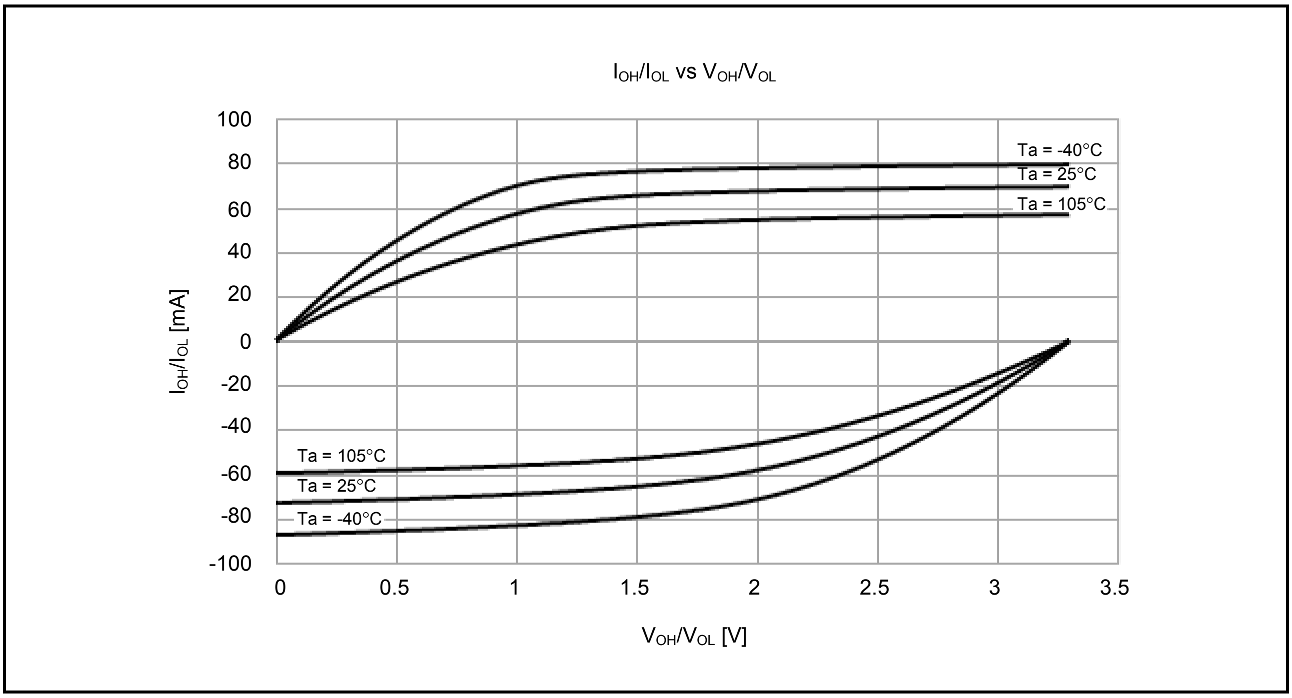


Figure 2.14 V_{OH}/V_{OL} and I_{OH}/I_{OL} temperature characteristics at VCC = 3.3 V when middle drive output is selected (reference data)

Table 2.11 Operating and standby current (1) (2 of 2)

Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter					Symbol	Typ*9	Max	Unit	Test Conditions
Supply current*1	Low-voltage mode*3	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 4 MHz	I_{CC}	1.5	-	mA	*7
			All peripheral clock disabled, CoreMark code executing from flash*5	ICLK = 4 MHz		1.4	-		
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 4 MHz		2.3	-		*8
			All peripheral clock enabled, code executing from flash*5	ICLK = 4 MHz		-	4.0		
		Sleep mode	All peripheral clock disabled*5	ICLK = 4 MHz		0.9	-		*7
			All peripheral clock enabled*5	ICLK = 4 MHz		1.7	-		*8
	Subosc-speed mode*4	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 32.768 kHz	I_{CC}	5.9	-	μA	*7
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 32.768 kHz		13.0	-		*8
			All peripheral clock enabled, code executing from flash*5	ICLK = 32.768 kHz		128.3 (17.8)*10	163.7		
		Sleep mode	All peripheral clock disabled*5	ICLK = 32.768 kHz		3.2	-		*7
			All peripheral clock enabled*5	ICLK = 32.768 kHz		10.0	-		*8

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.

Note 2. The clock source is HOCO.

Note 3. The clock source is MOCO.

Note 4. The clock source is the sub-clock oscillator.

Note 5. This does not include BGO operation.

Note 6. This is the increase for programming or erasure of the ROM or flash memory for data storage during program execution.

Note 7. PCLKB and PCLKD are set to divided by 64.

Note 8. PCLKB and PCLKD are the same frequency as that of ICLK.

Note 9. VCC = 3.3 V.

Note 10. MOCO and DAC is stopped.

Table 2.13 Operating and standby current (3)

Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter			Symbol	Min	Typ	Max	Unit	Test conditions
Operational Amplifier operating current	Low power mode	1-unit operating	I_{AMP}	-	1.0	2.0	μA	-
		2-unit operating		-	1.5	3.0	μA	-
		3-unit operating		-	2.0	3.5	μA	-
		4-unit operating		-	2.5	4.5	μA	-
	High speed mode	1-unit operating		-	200	280	μA	-
		2-unit operating		-	320	450	μA	-
		3-unit operating		-	440	620	μA	-
		4-unit operating		-	560	790	μA	-
USB operating current	During USB communication under the following settings and conditions: • Function controller is in Full-Speed mode and - Bulk OUT transfer is (64 bytes) × 1 - Bulk IN transfer is (64 bytes) × 1 • Host device is connected by a 1-meter USB cable from the USB port.		I_{USBF}*2	-	3.6 (VCC) 1.1 (VCC_USB)*4	-	mA	-
	During suspended state under the following setting and conditions: • Function controller is in Full-Speed mode (the USB_DP pin is pulled up) • Software Standby mode • Host device is connected by a 1-meter USB cable from the USB port.		I_{SUSP}*3	-	0.35 (VCC) 170 (VCC_USB)*4	-	μA	-
PWM Delay Generation Circuit current	PCLKD = 64 MHz, DLL Mode = 5-bit mode		I_{CC}	-	3.3	4.6	mA	-
	PCLKD = 64 MHz, DLL Mode = 4-bit mode			-	3.0	4.2	mA	-
	PCLKD = 32 MHz, DLL Mode = 5-bit mode			-	2.0	2.8	mA	-

Note 1. The reference power supply current is included in the power supply current value for D/A conversion.

Note 2. Current is consumed only by the USBFS.

Note 3. Includes the current supplied from the pull-up resistor of the USB_DP pin to the pull-down resistor of the host device, in addition to the current consumed by the MCU in the suspended state.

Note 4. When VCC = VCC_USB = 3.3 V.

Note 5. When the MCU is in Software Standby mode or the MSTPCRD.MSTPD16 (ADC140 module-stop bit) is in the module-stop state.

Table 2.18 Operation frequency in low-speed mode

Conditions: VCC = AVCC0 = 1.8 to 5.5 V

Parameter			Symbol	Min	Typ	Max*5	Unit
Operation frequency	System clock (ICLK)*1, *2, *4	1.8 to 5.5 V	f	0.032768	-	1	MHz
	Peripheral module clock (PCLKB)*4	1.8 to 5.5 V		-	-	1	
	Peripheral module clock (PCLKD)*3, *4	1.8 to 5.5 V		-	-	1	

Note 1. The lower-limit frequency of ICLK is 1 MHz while programming or erasing the flash memory.
Note 2. The frequency accuracy of ICLK must be ±3.5% during programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 1 MHz when the A/D converter is in use.
Note 4. See section 8, Clock Generation Circuit in User's Manual for the relationship of frequencies between ICLK, PCLKB, and PCLKD.
Note 5. The maximum value of operation frequency does not include internal oscillator errors. For details on the range of guaranteed operation, see Table 2.21, Clock timing.

Table 2.19 Operation frequency in low-voltage mode

Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter			Symbol	Min	Typ	Max*5	Unit
Operation frequency	System clock (ICLK)*1, *2, *4	1.6 to 5.5 V	f	0.032768	-	4	MHz
	Peripheral module clock (PCLKB)*4	1.6 to 5.5 V		-	-	4	
	Peripheral module clock (PCLKD)*3, *4	1.6 to 5.5 V		-	-	4	

Note 1. The lower-limit frequency of ICLK is 1 MHz while programming or erasing the flash memory. When using ICLK for programming or erasing the flash memory at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of ICLK must be ±3.5% during programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the 14-bit A/D converter is in use.
Note 4. See section 8, Clock Generation Circuit in User's Manual for the relationship of frequencies between ICLK, PCLKB, and PCLKD.
Note 5. The maximum value of operation frequency does not include internal oscillator errors. For details on the range of guaranteed operation, see Table 2.21, Clock timing.

Table 2.20 Operation frequency in Subosc-speed mode

Conditions: VCC = AVCC0 = 1.8 to 5.5 V

Parameter			Symbol	Min	Typ	Max	Unit
Operation frequency	System clock (ICLK)*1, *3	1.8 to 5.5 V	f	27.8528	32.768	37.6832	kHz
	Peripheral module clock (PCLKB)*3	1.8 to 5.5 V		-	-	37.6832	
	Peripheral module clock (PCLKD)*2, *3	1.8 to 5.5 V		-	-	37.6832	

Note 1. Programming and erasing the flash memory is not possible.
Note 2. The 14-bit A/D converter cannot be used.
Note 3. See section 8, Clock Generation Circuit in User's Manual for the relationship between ICLK, PCLKB, and PCLKD frequencies.

2.3.2 Clock Timing

Table 2.21 Clock timing (1 of 2)

Parameter		Symbol	Min	Typ	Max	Unit	Test conditions
EXTAL external clock input cycle time		t_{Xcyc}	50	-	-	ns	Figure 2.25
EXTAL external clock input high pulse width		t_{XH}	20	-	-	ns	
EXTAL external clock input low pulse width		t_{XL}	20	-	-	ns	
EXTAL external clock rising time		t_{Xr}	-	-	5	ns	
EXTAL external clock falling time		t_{Xf}	-	-	5	ns	
EXTAL external clock input wait time*1		t_{EXWT}	0.3	-	-	μs	-
EXTAL external clock input frequency		f_{EXTAL}	-	-	20	MHz	2.4 ≤ VCC ≤ 5.5
			-	-	8		1.8 ≤ VCC < 2.4
			-	-	1		1.6 ≤ VCC < 1.8
Main clock oscillator oscillation frequency		f_{MAIN}	1	-	20	MHz	2.4 ≤ VCC ≤ 5.5
			1	-	8		1.8 ≤ VCC < 2.4
			1	-	4		1.6 ≤ VCC < 1.8
LOCO clock oscillation frequency		f_{LOCO}	27.8528	32.768	37.6832	kHz	-
LOCO clock oscillation stabilization time		t_{LOCO}	-	-	100	μs	Figure 2.26
IWDT-dedicated clock oscillation frequency		f_{ILOCO}	12.75	15	17.25	kHz	-
MOCO clock oscillation frequency		f_{MOCO}	6.8	8	9.2	MHz	-
MOCO clock oscillation stabilization time		t_{MOCO}	-	-	1	μs	-
HOCO clock oscillation frequency		f_{HOCO24}	23.64	24	24.36	MHz	Ta = –40 to –20°C 1.8 ≤ VCC ≤ 5.5
			22.68	24	25.32		Ta = –40 to –85°C 1.6 ≤ VCC < 1.8
			23.76	24	24.24		Ta = –20 to 85°C 1.8 ≤ VCC ≤ 5.5
			23.52	24	24.48		Ta = 85 to 105°C 2.4 ≤ VCC ≤ 5.5
		f_{HOCO32}	31.52	32	32.48		Ta = –40 to –20°C 1.8 ≤ VCC ≤ 5.5
			30.24	32	33.76		Ta = –40 to 85°C 1.6 ≤ VCC < 1.8
			31.68	32	32.32		Ta = –20 to 85°C 1.8 ≤ VCC ≤ 5.5
			31.36	32	32.64		Ta = 85 to 105°C 2.4 ≤ VCC ≤ 5.5
		f_{HOCO48}*3	47.28	48	48.72		Ta = –40 to –20°C 1.8 ≤ VCC ≤ 5.5
			47.52	48	48.48		Ta = –20 to 85°C 1.8 ≤ VCC ≤ 5.5
			47.04	48	48.96		Ta = –40 to 105°C 2.4 ≤ VCC ≤ 5.5
		f_{HOCO64}*4	63.04	64	64.96		Ta = –40 to –20°C 2.4 ≤ VCC ≤ 5.5
			63.36	64	64.64		Ta = –20 to 85°C 2.4 ≤ VCC ≤ 5.5
			62.72	64	65.28		Ta = 85 to 105°C 2.4 ≤ VCC ≤ 5.5
HOCO clock oscillation stabilization time*5, *6	Except low-voltage mode	t_{HOCO24} t_{HOCO32}	-	-	37.1	μs	Figure 2.27
		t_{HOCO48}	-	-	43.3		
		t_{HOCO64}	-	-	80.6		
	Low-voltage mode	t_{HOCO24} t_{HOCO32} t_{HOCO48} t_{HOCO64}	-	-	100.9		
Sub-clock oscillator oscillation frequency		f_{SUB}	-	32.768	-	kHz	-

Note 1. The differences among lines in 1-LSB resolution are normalized by this value.
Note 2. The drive capability of the PWM delay generation circuit output port is middle drive.

2.3.8 CAC Timing

Table 2.32 CAC timing

Parameter			Symbol	Min	Typ	Max	Unit	Test conditions
CAC	CACREF input pulse width	t_{Pcyc} *1 ≤ t_{cac} *2	t_{CACREF}	$4.5 \times t_{cac} + 3 \times t_{Pcyc}$	-	-	ns	-
		t_{Pcyc} *1 > t_{cac} *2		$5 \times t_{cac} + 6.5 \times t_{Pcyc}$	-	-	ns	

Note 1. t_{Pcyc}: PCLKB cycle.
Note 2. t_{cac}: CAC count clock source cycle.

2.3.9 SCI Timing

Table 2.33 SCI timing (1)
Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter				Symbol	Min	Max	Unit*1	Test conditions
SCI	Input clock cycle	Asynchronous		t_{Scyc}	4	-	t_{Pcyc}	Figure 2.41
		Clock synchronous			6	-		
	Input clock pulse width			t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time			t_{SCKr}	-	20	ns	
	Input clock fall time			t_{SCKf}	-	20	ns	
	Output clock cycle	Asynchronous		t_{Scyc}	6	-	t_{Pcyc}	
		Clock synchronous			4	-		
	Output clock pulse width			t_{SCKW}	0.4	0.6	t_{Scyc}	
	Output clock rise time		1.8V or above	t_{SCKr}	-	20	ns	
			1.6V or above		-	30		
	Output clock fall time		1.8V or above	t_{SCKf}	-	20	ns	
			1.6V or above		-	30		
	Transmit data delay (master)	Clock synchronous	1.8V or above	t_{TXD}	-	40	ns	Figure 2.42
			1.6V or above		-	45		
	Transmit data delay (slave)	Clock synchronous	2.7V or above		-	55	ns	
			2.4V or above		-	60		
			1.8V or above		-	100		
			1.6V or above		-	125		
	Receive data setup time (master)	Clock synchronous	2.7V or above	t_{RXS}	45	-	ns	
			2.4V or above		55	-		
			1.8V or above		90	-		
			1.6V or above		110	-		
	Receive data setup time (slave)	Clock synchronous	2.7V or above		40	-	ns	
			1.6V or above		45	-		
	Receive data hold time (master)	Clock synchronous		t_{RXH}	5	-	ns	
	Receive data hold time (slave)	Clock synchronous		t_{RXH}	40	-	ns	

Note 1. t_{Pcyc}: PCLKB cycle.

Table 2.41 A/D conversion characteristics (1) in high-speed A/D conversion mode (2 of 2)

Conditions: VCC = AVCC0 = 4.5 to 5.5 V, VREFH0 = 4.5 to 5.5 V, VSS = AVSS0 = VREFL0 = 0V
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter	Min	Typ	Max	Unit	Test Conditions
Offset error	-	±2.0	±18	LSB	High-precision channel
			±24.0	LSB	Other than above
Full-scale error	-	±3.0	±18	LSB	High-precision channel
			±24.0	LSB	Other than above
Quantization error	-	±0.5	-	LSB	-
Absolute accuracy	-	±5.0	±20	LSB	High-precision channel
			±32.0	LSB	Other than above
DNL differential nonlinearity error	-	±4.0	-	LSB	-
INL integral nonlinearity error	-	±4.0	±12.0	LSB	-

Note: The characteristics apply when no pin functions other than 14-bit A/D converter input are used. Absolute accuracy does not include quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. The number of sampling states is indicated for the test conditions.

Table 2.42 A/D conversion characteristics (2) in high-speed A/D conversion mode (1 of 2)

Conditions: VCC = AVCC0 = 2.7 to 5.5 V, VREFH0 = 2.7 to 5.5 V, VSS = AVSS0 = VREFL0 = 0V
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter		Min	Typ	Max	Unit	Test Conditions
Frequency		1	-	48	MHz	-
Analog input capacitance	Cs	-	-	15	pF	High-precision channel
		-	-	30	pF	Normal-precision channel
Analog input resistance	Rs	-	-	2.5	kΩ	-
Analog input voltage range	Ain	0	-	VREFH0	V	-
12-bit mode						
Resolution		-	-	12	Bit	-
Conversion time*1 (Operation at PCLKD = 48 MHz)	Permissible signal source impedance Max. = 0.3 kΩ	0.94	-	-	μs	High-precision channel ADCSR.ADHSC = 0 ADSSTRn.SST[7:0] = 0Dh
		1.50	-	-	μs	Normal-precision channel ADCSR.ADHSC = 0 ADSSTRn.SST[7:0] = 28h
Offset error		-	±0.5	±4.5	LSB	High-precision channel
				±6.0	LSB	Other than above
Full-scale error		-	±0.75	±4.5	LSB	High-precision channel
				±6.0	LSB	Other than above
Quantization error		-	±0.5	-	LSB	-
Absolute accuracy		-	±1.25	±5.0	LSB	High-precision channel
				±8.0	LSB	Other than above
DNL differential nonlinearity error		-	±1.0	-	LSB	-
INL integral nonlinearity error		-	±1.0	±3.0	LSB	-
14-bit mode						
Resolution		-	-	14	Bit	-
Conversion time*1 (Operation at PCLKD = 48 MHz)	Permissible signal source impedance Max. = 0.3 kΩ	1.06	-	-	μs	High-precision channel ADCSR.ADHSC = 0 ADSSTRn.SST[7:0] = 0Dh
		1.63	-	-	μs	Normal-precision channel ADCSR.ADHSC = 0 ADSSTRn.SST[7:0] = 28h

Table 2.43 A/D conversion characteristics (3) in high-speed A/D conversion mode (2 of 2)
Conditions: VCC = AVCC0 = 2.4 to 5.5 V, VREFH0 = 2.4 to 5.5 V, VSS = AVSS0 = VREFL0 = 0V
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter	Min	Typ	Max	Unit	Test Conditions
Offset error	-	±2.0	±18	LSB	High-precision channel
			±24.0	LSB	Other than above
Full-scale error	-	±3.0	±18	LSB	High-precision channel
			±24.0	LSB	Other than above
Quantization error	-	±0.5	-	LSB	-
Absolute accuracy	-	±5.0	±20	LSB	High-precision channel
			±32.0	LSB	Other than above
DNL differential nonlinearity error	-	±4.0	-	LSB	-
INL integral nonlinearity error	-	±4.0	±12.0	LSB	-

Note: The characteristics apply when no pin functions other than 14-bit A/D converter input are used. Absolute accuracy does not include quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. The number of sampling states is indicated for the test conditions.

Table 2.44 A/D conversion characteristics (4) in low-power A/D conversion mode (1 of 2)
Conditions: VCC = AVCC0 = 2.7 to 5.5 V, VREFH0 = 2.7 to 5.5 V, VSS = AVSS0 = VREFL0 = 0V
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter		Min	Typ	Max	Unit	Test Conditions
Frequency		1	-	24	MHz	-
Analog input capacitance	Cs	-	-	15	pF	High-precision channel
		-	-	30	pF	Normal-precision channel
Analog input resistance	Rs	-	-	2.5	kΩ	-
Analog input voltage range	Ain	0	-	VREFH0	V	-
12-bit mode						
Resolution		-	-	12	Bit	-
Conversion time*1 (Operation at PCLKD = 24 MHz)	Permissible signal source impedance Max. = 1.1 kΩ	2.25	-	-	μs	High-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 0Dh
		3.38	-	-	μs	Normal-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 28h
Offset error		-	±0.5	±4.5	LSB	High-precision channel
				±6.0	LSB	Other than above
Full-scale error		-	±0.75	±4.5	LSB	High-precision channel
				±6.0	LSB	Other than above
Quantization error		-	±0.5	-	LSB	-
Absolute accuracy		-	±1.25	±5.0	LSB	High-precision channel
				±8.0	LSB	Other than above
DNL differential nonlinearity error		-	±1.0	-	LSB	-
INL integral nonlinearity error		-	±1.0	±3.0	LSB	-
14-bit mode						
Resolution		-	-	14	Bit	-
Conversion time*1 (Operation at PCLKD = 24 MHz)	Permissible signal source impedance Max. = 1.1 kΩ	2.50	-	-	μs	High-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 0Dh
		3.63	-	-	μs	Normal-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 28h

Table 2.44 A/D conversion characteristics (4) in low-power A/D conversion mode (2 of 2)
Conditions: VCC = AVCC0 = 2.7 to 5.5 V, VREFH0 = 2.7 to 5.5 V, VSS = AVSS0 = VREFL0 = 0V
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter	Min	Typ	Max	Unit	Test Conditions
Offset error	-	±2.0	±18	LSB	High-precision channel
			±24.0	LSB	Other than above
Full-scale error	-	±3.0	±18	LSB	High-precision channel
			±24.0	LSB	Other than above
Quantization error	-	±0.5	-	LSB	-
Absolute accuracy	-	±5.0	±20	LSB	High-precision channel
			±32.0	LSB	Other than above
DNL differential nonlinearity error	-	±4.0	-	LSB	-
INL integral nonlinearity error	-	±4.0	±12.0	LSB	-

Note: The characteristics apply when no pin functions other than 14-bit A/D converter input are used. Absolute accuracy does not include quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. The number of sampling states is indicated for the test conditions.

Table 2.45 A/D conversion characteristics (5) in low-power A/D conversion mode (1 of 2)
Conditions: VCC = AVCC0 = 2.4 to 5.5 V, VREFH0 = 2.4 to 5.5 V, VSS = AVSS0 = VREFL0 = 0V
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter		Min	Typ	Max	Unit	Test Conditions
Frequency		1	-	16	MHz	-
Analog input capacitance	Cs	-	-	15	pF	High-precision channel
		-	-	30	pF	Normal-precision channel
Analog input resistance	Rs	-	-	2.5	kΩ	-
Analog input voltage range	Ain	0	-	VREFH0	V	-
12-bit mode						
Resolution		-	-	12	Bit	-
Conversion time*1 (Operation at PCLKD = 16 MHz)	Permissible signal source impedance Max. = 2.2 kΩ	3.38	-	-	μs	High-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 0Dh
		5.06	-	-	μs	Normal-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 28h
Offset error		-	±0.5	±4.5	LSB	High-precision channel
				±6.0	LSB	Other than above
Full-scale error		-	±0.75	±4.5	LSB	High-precision channel
				±6.0	LSB	Other than above
Quantization error		-	±0.5	-	LSB	-
Absolute accuracy		-	±1.25	±5.0	LSB	High-precision channel
				±8.0	LSB	Other than above
DNL differential nonlinearity error		-	±1.0	-	LSB	-
INL integral nonlinearity error		-	±1.0	±3.0	LSB	-
14-bit mode						
Resolution		-	-	14	Bit	-
Conversion time*1 (Operation at PCLKD = 16 MHz)	Permissible signal source impedance Max. = 2.2 kΩ	3.75	-	-	μs	High-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 0Dh
		5.44	-	-	μs	Normal-precision channel ADCSR.ADHSC = 1 ADSSTRn.SST[7:0] = 28h

Table 2.47 A/D conversion characteristics (7) in low-power A/D conversion mode (2 of 2)

Conditions: VCC = AVCC0 = 1.6 to 5.5 V (AVCC0 = VCC when VCC < 2.0 V), VREFH0 = 1.6 to 5.5 V, VSS = AVSS0 = VREFL0 = 0
Reference voltage range applied to the VREFH0 and VREFL0.

Parameter	Min	Typ	Max	Unit	Test Conditions
Offset error	-	±4.0	±30.0	LSB	High-precision channel
			±40.0	LSB	Other than above
Full-scale error	-	±6.0	±30.0	LSB	High-precision channel
			±40.0	LSB	Other than above
Quantization error	-	±0.5	-	LSB	-
Absolute accuracy	-	±12.0	±32.0	LSB	High-precision channel
			±48.0	LSB	Other than above
DNL differential nonlinearity error	-	±4.0	-	LSB	-
INL integral nonlinearity error	-	±4.0	±12.0	LSB	-

Note: The characteristics apply when no pin functions other than 14-bit A/D converter input are used. Absolute accuracy does not include quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. The number of sampling states is indicated for the test conditions.

Table 2.48 14-bit A/D converter channel classification

Classification	Channel	Conditions	Remarks
High-precision channel	AN000 to AN013	AVCC0 = 1.6 to 5.5 V	Pins AN000 to AN013 cannot be used as general I/O, IRQ2 input, or for TS transmission when the A/D converter is in use.
Normal-precision channel	AN016 to AN022		-
Internal reference voltage input channel	Internal reference voltage	AVCC0 = 2.0 to 5.5 V	-
Temperature sensor input channel	Temperature sensor output	AVCC0 = 2.0 to 5.5 V	-

Table 2.49 A/D internal reference voltage characteristics

Conditions: VCC = AVCC0 = VREFH0 = 2.0 to 5.5 V*1

Parameter	Min	Typ	Max	Unit	Test conditions
Internal reference voltage input channel*2	1.36	1.43	1.50	V	-
Sampling time	5.0	-	-	μs	-

Note 1. The internal reference voltage cannot be selected for input channels when AVCC0 < 2.0 V.

Note 2. The 14-bit A/D internal reference voltage indicates the voltage when the internal reference voltage is input to the 14-bit A/D converter.

Table 2.61 Code flash characteristics (3)

Middle-speed operating mode

Conditions: VCC = AVCC0 = 1.8 to 5.5 V, Ta = –40 to +85°C

Parameter		Symbol	ICLK = 1 MHz			ICLK = 8 MHz			Unit
			Min	Typ	Max	Min	Typ	Max	
Programming time	4 bytes	t_{P4}	-	157	1411	-	101	966	μs
Erasure time	1 KB	t_{E1K}	-	9.10	289	-	6.10	228	ms
Blank check time	2 bytes	t_{BC4}	-	-	87.7	-	-	52.5	μs
	1 KB	t_{BC1K}	-	-	1930	-	-	414	μs
Erase suspended time		t_{SED}	-	-	32.7	-	-	21.6	μs
Startup area switching setting time		t_{SAS}	-	22.8	592	-	14.2	465	ms
Access window time		t_{AWS}	-	22.8	592	-	14.2	465	ms
OCD/serial programmer ID setting time		t_{OSIS}	-	22.8	592	-	14.2	465	ms
Flash memory mode transition wait time 1		t_{DIS}	2	-	-	2	-	-	μs
Flash memory mode transition wait time 2		t_{MS}	720	-	-	720	-	-	ns

Note 1. Does not include the time until each operation of the flash memory is started after instructions are executed by the software.

Note 2. The lower-limit frequency of ICLK is 1 MHz during programming or erasing the flash memory. When using ICLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note 3. The frequency accuracy of ICLK must be ±3.5% during programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.

2.13.2 Data Flash Memory Characteristics

Table 2.62 Data flash characteristics (1)

Parameter		Symbol	Min	Typ	Max	Unit	Conditions
Reprogramming/erasure cycle*1		N_{DPEC}	100000	1000000	-	Times	-
Data hold time	After 10000 times of N_{DPEC}	t_{DDRP}	20*2, *3	-	-	Year	Ta = +85°C
	After 100000 times of N_{DPEC}		5*2, *3	-	-	Year	
	After 1000000 times of N_{DPEC}		-	1*2, *3	-	Year	Ta = +25°C

Note 1. The reprogram/erase cycle is the number of erasure for each block. When the reprogram/erase cycle is n times (n = 100,000), erasing can be performed n times for each block. For instance, when 1-byte programming is performed 1,000 times for different addresses in 1-byte blocks, and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasure is not enabled. (overwriting is prohibited.)

Note 2. Characteristics when using the flash memory programmer and the self-programming library provided by Renesas Electronics.

Note 3. These results are obtained from reliability testing.

Table 2.65 SWD characteristics (1) (2 of 2)
Conditions: VCC = AVCC0 = 2.4 to 5.5 V

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
SWDIO setup time	t_{SWDS}	16	-	-	ns	Figure 2.70
SWDIO hold time	t_{SWDH}	16	-	-	ns	
SWDIO data delay time	t_{SWDD}	2	-	70	ns	

Table 2.66 SWD characteristics (2)
Conditions: VCC = AVCC0 = 1.6 to 2.4 V

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
SWCLK clock cycle time	$t_{SWCKcyc}$	250	-	-	ns	Figure 2.69
SWCLK clock high pulse width	t_{SWCKH}	120	-	-	ns	
SWCLK clock low pulse width	t_{SWCKL}	120	-	-	ns	
SWCLK clock rise time	t_{SWCKr}	-	-	5	ns	
SWCLK clock fall time	t_{SWCKf}	-	-	5	ns	
SWDIO setup time	t_{SWDS}	50	-	-	ns	Figure 2.70
SWDIO hold time	t_{SWDH}	50	-	-	ns	
SWDIO data delay time	t_{SWDD}	2	-	150	ns	

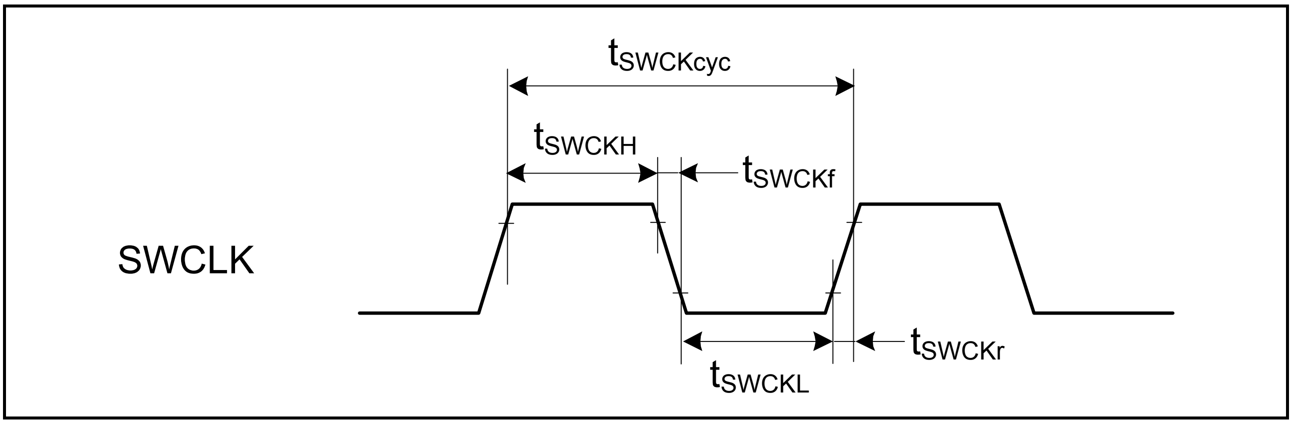
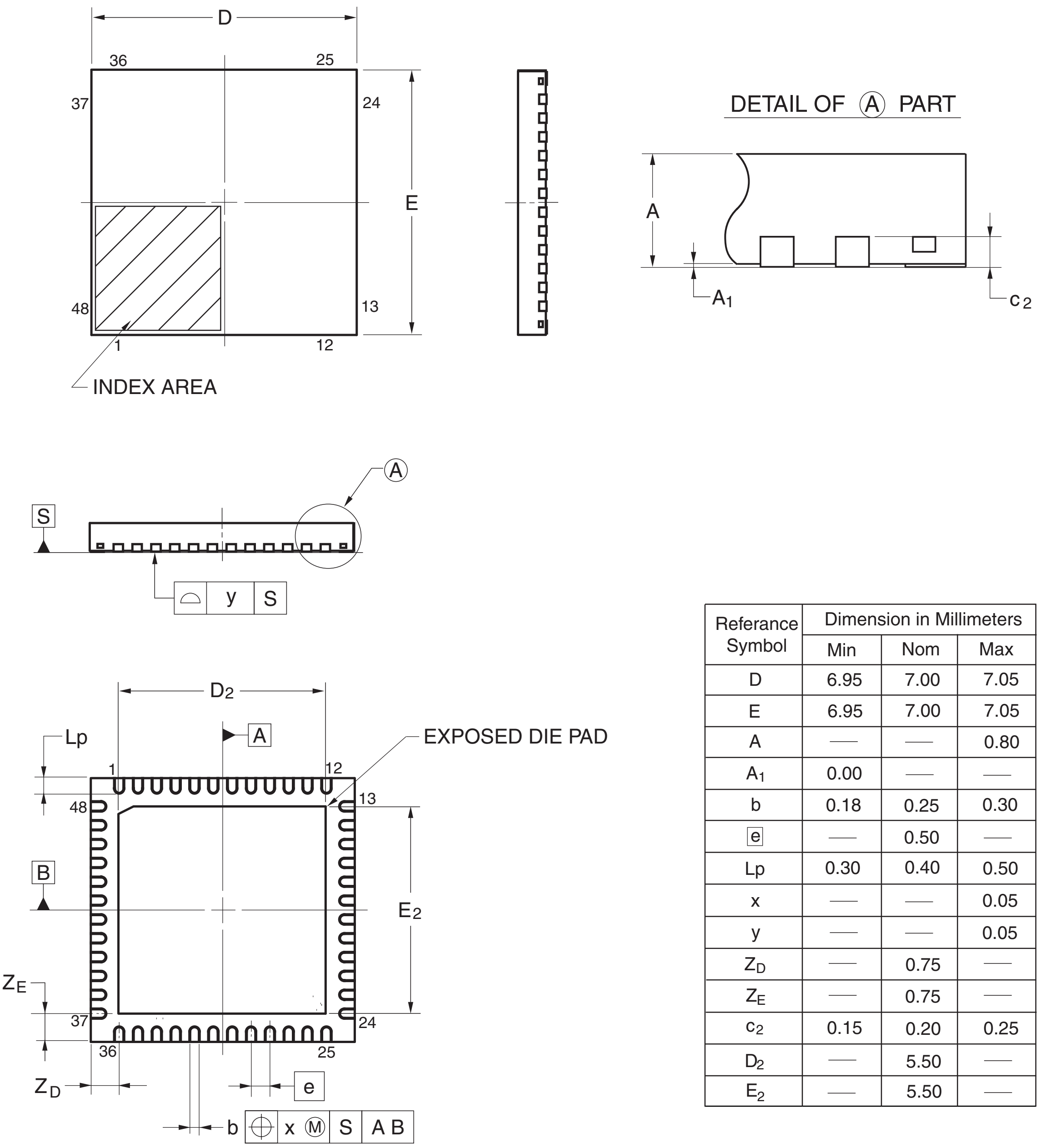


Figure 2.69 SWD SWCLK timing

JEITA Package code	RENESAS code	Previous code	MASS(TYP.)[g]
P-HWQFN48-7x7-0.50	PWQN0048KB-A	48PJN-A P48K8-50-5B4-6	0.13



Referance Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.95	7.00	7.05
E	6.95	7.00	7.05
A	—	—	0.80
A_1	0.00	—	—
b	0.18	0.25	0.30
e	—	0.50	—
Lp	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05
Z_D	—	0.75	—
Z_E	—	0.75	—
c_2	0.15	0.20	0.25
D_2	—	5.50	—
E_2	—	5.50	—

Figure 1.5 QFN 48-pin

S128 Microcontroller Datasheet

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